In re application of:

Application No.

Filed: For:

Group No.

Examiner:

Jun Young Yang

09/687,493

October 13, 2000

SEMICONDUCTOR PACKAGE HAVING IMPROVED ADHESIVENESS AND GROUND BONDING

2811

(Not Yet Known)

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Washington, D.C. 20231

Signature: Sara J. Morrison

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## RESPONSE TO NOTICE TO FILE MISSING PARTS OF NONPROVISIONAL APPLICATION FILED UNDER 37 CFR §1.53(b) FILING DATE GRANTED

This is a response to the Notice of Missing Parts of Application - Filing Date Granted mailed on November 27, 2000.